504588791 10/11/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT4635503 Stylesheet Version v1.2

SUBMISSION TYPE: CORRECTIVE ASSIGNMENT **NATURE OF CONVEYANCE:** Corrective Assignment to correct the MISSPELLING IN ASSIGNEE'S NAME previously recorded on Reel 035874 Frame 0694. Assignor(s) hereby confirms the CORRECTIVE ASSIGNMENT.

CONVEYING PARTY DATA

Name	Execution Date
SHINN-SHENG YU	07/22/2013
ANTHONY YEN	07/21/2013

RECEIVING PARTY DATA

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City: HSIN-CHU		
State/Country: TAIWAN		
Postal Code: 300-77		

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14733719	

CORRESPONDENCE DATA

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	20111650 / 24061.2114US02
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM
SIGNATURE:	/Janie Martinez-Holm/
DATE SIGNED:	10/11/2017

Total Attachments: 4

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PATENT REEL: 044175 FRAME: 0094

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> PATENT REEL: 044175 FRAME: 0095

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PATENT ASSIGNMENT COVER SHEET

06/22/2015

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3406206

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
SHINN-SHENG YU		07/22/2013
ANTHONY YEN		07/21/2013

RECEIVING PARTY DATA		MANUFACTURIN
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Traine:	
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Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type		Number		
	Application Number:	14733719		

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	20111650/24061.2114US02	
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM	
SIGNATURE:	/Janie Martinez-Holm/	
DATE SIGNED:	06/22/2015	

Total Attachments: 2

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> **PATENT** REEL: 044175 FRAME: 0096

Docket No.: 2011-1650/24061.2114

Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

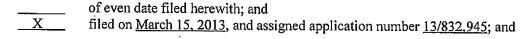
(1)	Shinn-Sheng Yu	of	4F-2 No. 16, Lane 634, Nanda Road,
			Hsinchu, Taiwan, R.O.C.

(2) Anthony Yen of 17F, 296-5 Guangming 6th Road, E. Sec. 1, Zhubei City, Hsinchu County, Taiwan 302, R.O.C.

have invented certain improvements in

A LITHOGRAPHY PROCESS

for which we have executed an application for Letters Patent of the United States of America,



WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths

-1-

Docket No.: 2011-1650/24061.2114

Customer No.: 000042717

and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Shinn-Sheng Yu

Residence Address:

4F-2 No. 16, Lane 634, Nanda Road, Hsinchu, Taiwan, R.O.C.

Dated: 2013/07/22

Inventor Signature

Inventor Name:

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Dated: (July 21, 201

Inventor Signature